

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



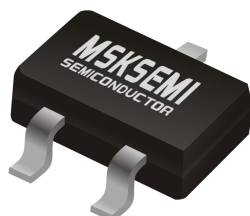
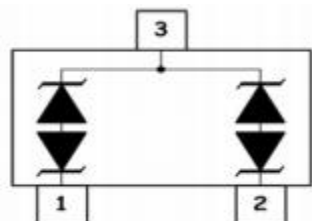
GDT



PLED

Product data sheet

PIN CONFIGURATION



SOT-23

FEATURES

- ✧ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ 350 Watts Peak Pulse Power per (tp=8/20μs)
- ✧ Protects two bidirectional lines
- ✧ Low clamping voltage
- ✧ Working voltages: 3.3V to 36V
- ✧ Low leakage current

MACHANICAL DATA

- ✧ SOT-23 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ High temperature soldering guaranteed:
260C/10s
- ✧ Reel size: 7 inch
- ✧ MSL 1

APPLICATIONS

- ✧ Cell Phone Handsets and Accessories
- ✧ Microprocessor based equipment
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Networking and Telecom
- ✧ Serial and Parallel Ports.
- ✧ Peripherals

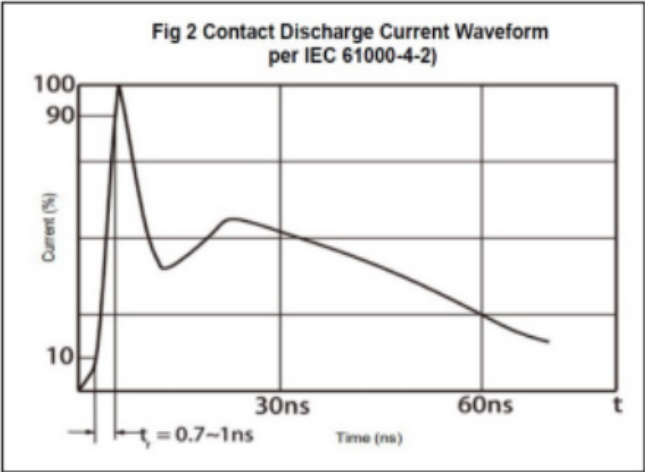
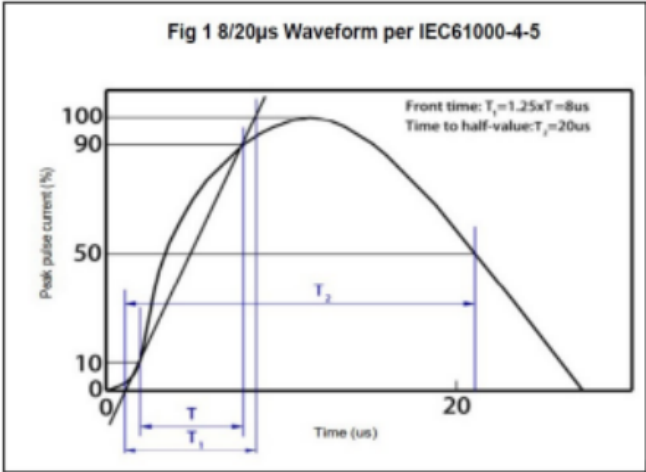
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact)	± 30	kV
	ESD per IEC 61000-4-2 (Air)	± 30	
P_{PP}	Peak Pulse Power (8/20μs)	350	W
T_{OPT}	Operating Temperature	-55/+150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-55/+150	$^{\circ}\text{C}$
T_{L}	Lead Soldering Temperature	260 (10 sec.)	$^{\circ}\text{C}$

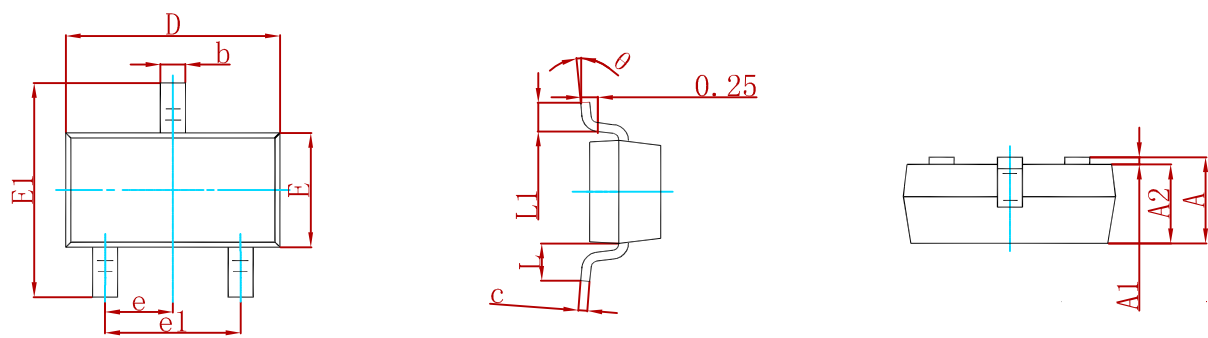
ELECTRICAL CHARACTERISTICS (Tamb=25⁰C)

P/N	MARK	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _{C@1A} (V) (max.)	V _C (V) (max.) (@A)		I _R (μA) (max.)	C _J (pF) (max.)
SDT23C05L02-MS	C05	5.0	6.0	1	9.8	18.0	17	10	200
SDT23C12L02-MS	C12	12.0	13.3	1	19.0	32.0	11	1	75
SDT23C15L02-MS	C15	15.0	16.7	1	24.0	38.0	10	1	68
SDT23C24L02-MS	C24	24.0	26.7	1	43.0	52.0	7	1	50

ELECTRICAL CHARACTERISTICS CURVE

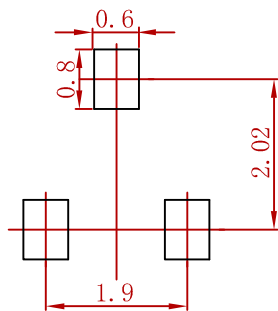


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:
- 1.Controlling dimension:in millimeters.
 - 2.General tolerance:± 0.05mm.
 - 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SDT23CXXL02-MS	SOT-23	3000

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